

WHAT IS CLAIMED IS:

1. A solid-state image pickup apparatus comprising:  
a solid-state image pickup device chip having a bump formed thereon, and  
a hermetic seal portion provided over the solid-state image pickup device chip having a flat-plate portion formed of a transparent member and a frame portion disposed on a side portion of a lower surface of the flat-plate portion;  
said frame portion at least including a metal wiring, a bump formed on said solid-state image pickup device chip and electrically connected to the metal wiring, and a sealed region for sealing the periphery of the bump by a sealing material.
2. The solid-state image pickup apparatus according to claim 1, wherein said metal wiring is formed on the side portion of the lower surface of said flat-plate portion.
3. The solid-state image pickup apparatus according to claim 1, wherein said frame portion further includes a frame base portion and said metal wiring is formed on one surface of said frame base portion while the other surface of the frame base portion is adhered to said flat-plate portion.

4 . The solid-state image pickup apparatus according to claim 1, wherein an anisotropic conductive material is used as said sealing material.

5 . The solid-state image pickup apparatus according to claim 2, wherein an anisotropic conductive material is used as said sealing material.

6 . The solid-state image pickup apparatus according to claim 3, wherein an anisotropic conductive material is used as said sealing material.

7 . The solid-state image pickup apparatus according to claim 1, wherein said frame portion has a function for screening light based on a coloring or the like of said sealing material.

8 . The solid-state image pickup apparatus according to claim 2, wherein said frame portion has a function for screening light based on a coloring or the like of said sealing material.

9 . The solid-state image pickup apparatus according to claim 3, wherein said frame portion has a function for

screening light based on a coloring or the like of said sealing material or of said frame base portion.

10. The solid-state image pickup apparatus according to claim 4, wherein said frame portion has a function for screening light based on a coloring or the like of said sealing material.

11. The solid-state image pickup apparatus according to claim 5, wherein said frame portion has a function for screening light based on a coloring or the like of said sealing material.

12. The solid-state image pickup apparatus according to claim 6, wherein said frame portion has a function for screening light based on a coloring or the like of said sealing material or of said frame base portion.

13. The solid-state image pickup apparatus according to claim 1, wherein a wiring region or an electrode pad region is formed from an electrode pad provided on said solid-state image pickup device chip to a side surface or through a side surface to a back surface of said solid-state image pickup device chip so that an external terminal can be electrically connected to the wiring region or the

electrode pad region.

14. A fabricating method of solid-state image pickup apparatus having a hermetic seal portion provided over a solid-state image pickup device chip comprising a flat-plate portion formed of a transparent member and a frame portion disposed at a side portion of a lower surface of the flat-plate portion including the steps of:

over an entire wafer having a large number of solid-state image pickup device chips formed thereon, integrally and correspondingly to each individual solid-state image pickup device chip, forming a hermetic seal portion comprising a flat-plate portion made of a transparent member, and a frame portion disposed at a side portion of a lower surface of the flat-plate portion having a metal wiring, a bump formed on solid-state image pickup device chip and electrically connected to the metal wiring, and a seal region for sealing the periphery of the bump by a sealing material; and

separating the wafer having the integrally formed hermetic seal portions thereon into solid-state image pickup device chips each having an individual hermetic seal portion.